


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/17/9975	
<b>1.3 Title of PCN</b>	Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in BGA package	
<b>1.4 Product Category</b>	BGA packaged products	
<b>1.5 Issue date</b>	2017-02-17	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Michel BUFFA
<b>2.1.2 Marketing Manager</b>	Daniel COLONNA
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer...)	Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Current location : Stats ChipPAC Shanghai China (SCC)	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. Bill Of Materials (BOM) remains unchanged. Traceability is enhanced : 2 digits are added in the marking instruction.  See more information on PCN 9975 – Additional information document attached.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No change.	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only BGA packaged products.
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability is described in PCN9975_Additional information attached document
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2017-07-07
<b>7.2 Intended start of delivery</b>	2017-08-07
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	9975 PCN9975_RERMCD1624- LFBGA10x10 JSCC- MCD QA reliability plan.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-02-17
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9. Attachments (additional documentations)	
9975 Public product.pdf 9975 PCN9975_Additional information.pdf 9975 PCN9975_RERMCD1624- LFBGA10x10 JSCC- MCD QA reliability plan.pdf	

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F103VCH6	
	STM32F103VDH6	
	STM32F103VEH6	
	STM32F103ZDH6	
	STM32F103ZEH6	
	STM32F103ZGH6	
	STM32F107VCH6	
	STR710FZ2H6	
	STM32F103VBH7	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title** : Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in BGA package

**PCN Reference** : MDG/17/9975

**Subject** : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F103ZGH6JTR	STM32F103VCH6	STM32F103VBH6
STM32F103VEH6	STM32F103ZGH6TR	STM32F107VCH6
STM32F103VEH6TR	STM32F103VEH7	STM32F103ZEH6TR
STM32F103VDH6TR	STM32F103ZEH6	STM32F103ZGH6J
STM32F103ZFH6	STM32F103ZCH6	STM32F103ZGH6
STM32F103ZEH7	STR710RZH6	STM32F103ZFH6TR
STR710FZ2H6	STM32F103VBH7	STM32F103V8H6
STM32F103ZDH6	STR710FZ1H6	STM32F103ZGH7
STM32F103VDH6	STM32F103ZDH6TR	STM32F105VBH6



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